

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 1, line 10 of specification with the following paragraph.

21 -- Additionally, this application is related to the application "INJECTION MOLD FOR AN OPTICAL SEMICONDUCTOR PACKAGE AND CORRESPONDING OPTICAL SEMICONDUCTOR PACKAGE," Serial No. 09/862,984, now \_\_\_\_\_, which was filed on the same day as the present application and commonly assigned herewith to STMicroelectronics S.A. This related application is herein incorporated by reference.

IN THE CLAIMS:

Please amend claims 1, 5-7, 9, and 11-13, and add new claims 14-20 as follows:

1. (Amended) An injection mold for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said injection mold comprising:
- at least two parts that define at least one injection circuit formed between the two parts and in at least one of the parts, the injection circuit including:
    - at least one injection cavity for housing the chip;
    - at least one transfer chamber from which the encapsulation material is injected;
  - and
  - at least one injection channel formed in a parting line or plane of the mold, the at least one injection channel connecting the transfer chamber to the injection cavity; and
  - at least one blind complementary channel formed between the two parts of the mold and in at least one of the parts, the blind complementary channel directly communicating with the injection channel at some distance from the injection cavity and the transfer chamber such that the blind complementary channel causes the formation of at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection channel, so that if during injection molding flash is formed between the two parts of the mold in its parting line or plane, then after demolding such flash stays attached to at least the encapsulation material that filled the injection channel and the blind complementary channel.
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